

CMOS Hex Buffer/Converters

The CD4049UB and CD4050B devices are inverting and non-inverting hex buffers, respectively, and feature logic-level conversion using only one supply voltage (V_{CC}). The input-signal high level (V_{IH}) can exceed the V_{CC} supply voltage when these devices are used for logic-level conversions. These devices are intended for use as CMOS to DTL/TTL converters and can drive directly two DTL/TTL loads. ($V_{CC} = 5V$, $V_{OL} \leq 0.4V$, and $I_{OL} \geq 3.3mA$.)

The CD4049UB and CD4050B are designated as replacements for CD4009UB and CD4010B, respectively. Because the CD4049UB and CD4050B require only one power supply, they are preferred over the CD4009UB and CD4010B and should be used in place of the CD4009UB and CD4010B in all inverter, current driver, or logic-level conversion applications. In these applications the CD4049UB and CD4050B are pin compatible with the CD4009UB and CD4010B respectively, and can be substituted for these devices in existing as well as in new designs. Terminal No. 16 is not connected internally on the CD4049UB or CD4050B, therefore, connection to this terminal is of no consequence to circuit operation. For applications not requiring high sink-current or voltage conversion, the CD4069UB Hex Inverter is recommended.

Features

- CD4049UB Inverting
- CD4050B Non-Inverting
- High Sink Current for Driving 2 TTL Loads
- High-To-Low Level Logic Conversion
- 100% Tested for Quiescent Current at 20V
- Maximum Input Current of $1\mu A$ at 18V Over Full Package Temperature Range; 100nA at 18V and 25°C
- 5V, 10V and 15V Parametric Ratings

Applications

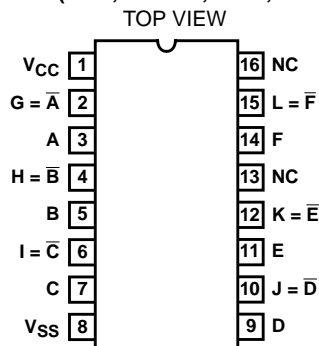
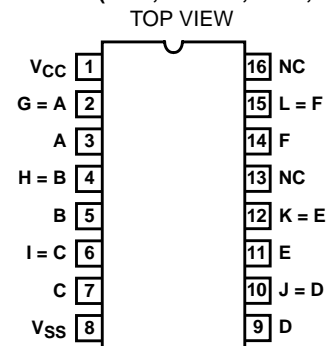
- CMOS to DTL/TTL Hex Converter
- CMOS Current "Sink" or "Source" Driver
- CMOS High-To-Low Logic Level Converter

Ordering Information

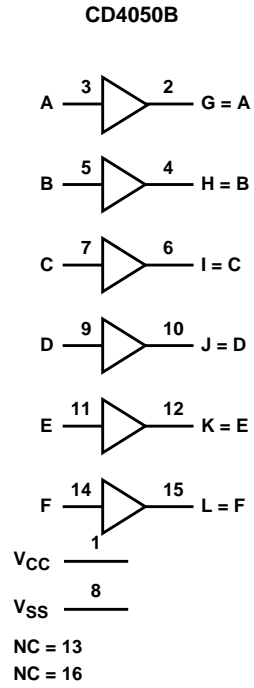
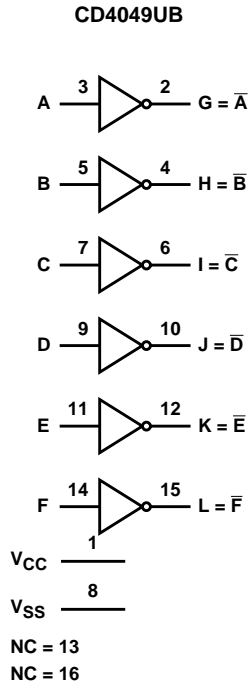
| PART NUMBER | TEMP. RANGE (°C) | PACKAGE |
|-------------|------------------|--------------|
| CD4049UBF3A | -55 to 125 | 16 Ld CERDIP |
| CD4050BF3A | -55 to 125 | 16 Ld CERDIP |
| CD4049UBD | -55 to 125 | 16 Ld SOIC |
| CD4049UBDR | -55 to 125 | 16 Ld SOIC |
| CD4049UBDT | -55 to 125 | 16 Ld SOIC |
| CD4049UBDW | -55 to 125 | 16 Ld SOIC |
| CD4049UBDWR | -55 to 125 | 16 Ld SOIC |
| CD4049UBE | -55 to 125 | 16 Ld PDIP |
| CD4049UBNSR | -55 to 125 | 16 Ld SOP |
| CD4049UBPW | -55 to 125 | 16 Ld TSSOP |
| CD4049UBPWR | -55 to 125 | 16 Ld TSSOP |
| CD4050BD | -55 to 125 | 16 Ld SOIC |
| CD4050BDR | -55 to 125 | 16 Ld SOIC |
| CD4050BDT | -55 to 125 | 16 Ld SOIC |
| CD4050BDW | -55 to 125 | 16 Ld SOIC |
| CD4050BDWR | -55 to 125 | 16 Ld SOIC |
| CD4050BE | -55 to 125 | 16 Ld PDIP |
| CD4050NSR | -55 to 125 | 16 Ld SOP |
| CD4050BPW | -55 to 125 | 16 Ld TSSOP |
| CD4050BPWR | -55 to 125 | 16 Ld TSSOP |

NOTE: When ordering, use the entire part number. The suffix R denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

Pinouts

CD4049UB (PDIP, CERDIP, SOIC, SOP, TSSOP)

CD4050B (PDIP, CERDIP, SOIC, SOP)


Functional Block Diagrams



Schematic Diagrams

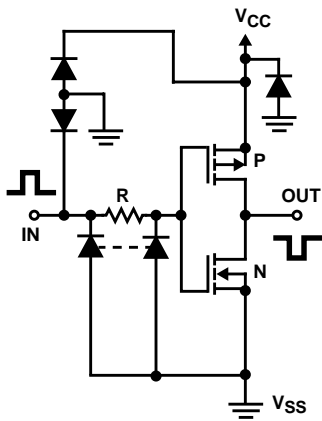


FIGURE 1A. SCHEMATIC DIAGRAM OF CD4049UB, 1 OF 6 IDENTICAL UNITS

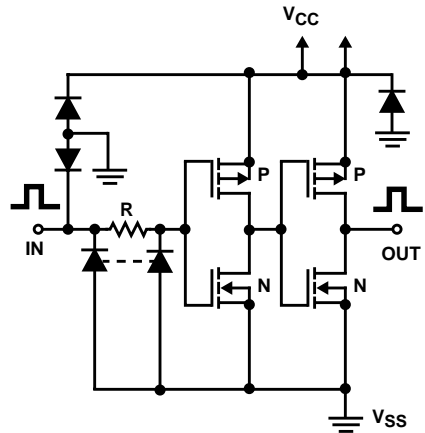


FIGURE 1B. SCHEMATIC DIAGRAM OF CD4050B, 1 OF 6 IDENTICAL UNITS

CD4049UB, CD4050B

Absolute Maximum Ratings

Supply Voltage (V+ to V-) -0.5V to 20V
 DC Input Current, Any One Input ±10mA

Operating Conditions

Temperature Range -55°C to 125°C

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note1):
 E (PDIP) Package 67°C/W
 D (SOIC) Package 73°C/W
 DW (SOIC) Package 57°C/W
 NS (SOP) Package 64°C/W
 PW (TSSOP) Package 108°C/W
 Maximum Junction Temperature (Plastic Package) 150°C
 Maximum Storage Temperature Range 65°C to 150°C
 Maximum Lead Temperature (Soldering 10s) 265°C
 SOIC - Lead Tips Only

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

| PARAMETER | TEST CONDITIONS | | | LIMITS AT INDICATED TEMPERATURE (°C) | | | | | | | UNITS |
|---|--------------------|---------------------|---------------------|--------------------------------------|-------|-------|-------|-------|------|------|-------|
| | | | | | | | 25 | | | | |
| | V _O (V) | V _{IN} (V) | V _{CC} (V) | -55 | -40 | 85 | 125 | MIN | TYP | MAX | |
| Quiescent Device Current I _{DD} (Max) | - | 0,5 | 5 | 1 | 1 | 30 | 30 | - | 0.02 | 1 | µA |
| | - | 0,10 | 10 | 2 | 2 | 60 | 60 | - | 0.02 | 2 | µA |
| | - | 0,15 | 15 | 4 | 4 | 120 | 120 | - | 0.02 | 4 | µA |
| | - | 0,20 | 20 | 20 | 20 | 600 | 600 | - | 0.04 | 20 | µA |
| Output Low (Sink) Current I _{OL} (Min) | 0.4 | 0,5 | 4.5 | 3.3 | 3.1 | 2.1 | 1.8 | 2.6 | 5.2 | - | mA |
| | 0.4 | 0,5 | 5 | 4 | 3.8 | 2.9 | 2.4 | 3.2 | 6.4 | - | mA |
| | 0.5 | 0,10 | 10 | 10 | 9.6 | 6.6 | 5.6 | 8 | 16 | - | mA |
| | 1.5 | 0,15 | 15 | 26 | 25 | 20 | 18 | 24 | 48 | - | mA |
| Output High (Source) Current I _{OH} (Min) | 4.6 | 0,5 | 5 | -0.81 | -0.73 | -0.58 | -0.48 | -0.65 | -1.2 | - | mA |
| | 2.5 | 0,5 | 5 | -2.6 | -2.4 | -1.9 | -1.55 | -2.1 | -3.9 | - | mA |
| | 9.5 | 0,10 | 10 | -2.0 | -1.8 | -1.35 | -1.18 | -1.65 | -3.0 | - | mA |
| | 13.5 | 0,15 | 15 | -5.2 | -4.8 | -3.5 | -3.1 | -4.3 | -8.0 | - | mA |
| Out Voltage Low Level V _{OL} (Max) | - | 0,5 | 5 | 0.05 | 0.05 | 0.05 | 0.05 | - | 0 | 0.05 | V |
| | - | 0,10 | 10 | 0.05 | 0.05 | 0.05 | 0.05 | - | 0 | 0.05 | V |
| | - | 0,15 | 15 | 0.05 | 0.05 | 0.05 | 0.05 | - | 0 | 0.05 | V |
| Output Voltage High Level V _{OH} (Min) | - | 0,5 | 5 | 4.95 | 4.95 | 4.95 | 4.95 | 4.95 | 5 | - | V |
| | - | 0,10 | 10 | 9.95 | 9.95 | 9.95 | 9.95 | 9.95 | 10 | - | V |
| | - | 0,15 | 15 | 14.95 | 14.95 | 14.95 | 14.95 | 14.95 | 15 | - | V |
| Input Low Voltage, V _{IL} (Max) CD4049UB | 4.5 | - | 5 | 1 | 1 | 1 | 1 | - | - | 1 | V |
| | 9 | - | 10 | 2 | 2 | 2 | 2 | - | - | 2 | V |
| | 13.5 | - | 15 | 2.5 | 2.5 | 2.5 | 2.5 | - | - | 2.5 | V |
| Input Low Voltage, V _{IL} (Max) CD4050B | 0.5 | - | 5 | 1.5 | 1.5 | 1.5 | 1.5 | - | - | 1.5 | V |
| | 1 | - | 10 | 3 | 3 | 3 | 3 | - | - | 3 | V |
| | 1.5 | - | 15 | 4 | 4 | 4 | 4 | - | - | 4 | V |

CD4049UB, CD4050B

DC Electrical Specifications (Continued)

| PARAMETER | TEST CONDITIONS | | | LIMITS AT INDICATED TEMPERATURE (°C) | | | | | | | UNITS |
|---|--------------------|---------------------|---------------------|--------------------------------------|------|------|------|------|-------------------|------|-------|
| | | | | 25 | | | | | | | |
| | V _O (V) | V _{IN} (V) | V _{CC} (V) | -55 | -40 | 85 | 125 | MIN | TYP | MAX | |
| Input High Voltage, V _{IH} Min CD4049UB | 0.5 | - | 5 | 4 | 4 | 4 | 4 | 4 | - | - | V |
| | 1 | - | 10 | 8 | 8 | 8 | 8 | 8 | - | - | V |
| | 1.5 | - | 15 | 12.5 | 12.5 | 12.5 | 12.5 | 12.5 | - | - | V |
| Input High Voltage, V _{IH} Min CD4050B | 4.5 | - | 5 | 3.5 | 3.5 | 3.5 | 3.5 | 3.5 | - | - | V |
| | 9 | - | 10 | 7 | 7 | 7 | 7 | 7 | - | - | V |
| | 13.5 | - | 15 | 11 | 11 | 11 | 11 | 11 | - | - | V |
| Input Current, I _{IN} Max | - | 0,18 | 18 | ±0.1 | ±0.1 | ±1 | ±1 | - | ±10 ⁻⁵ | ±0.1 | μA |

AC Electrical Specifications T_A = 25°C, Input t_r, t_f = 20ns, C_L = 50pF, R_L = 200kΩ

| PARAMETER | TEST CONDITIONS | | LIMITS (ALL PACKAGES) | | UNITS |
|---|-----------------|-----------------|-----------------------|-----|-------|
| | V _{IN} | V _{CC} | TYP | MAX | |
| Propagation Delay Time Low to High, t _{PLH} CD4049UB | 5 | 5 | 60 | 120 | ns |
| | 10 | 10 | 32 | 65 | ns |
| | 10 | 5 | 45 | 90 | ns |
| | 15 | 15 | 25 | 50 | ns |
| | 15 | 5 | 45 | 90 | ns |
| Propagation Delay Time Low to High, t _{PLH} CD4050B | 5 | 5 | 70 | 140 | ns |
| | 10 | 10 | 40 | 80 | ns |
| | 10 | 5 | 45 | 90 | ns |
| | 15 | 15 | 30 | 60 | ns |
| | 15 | 5 | 40 | 80 | ns |
| Propagation Delay Time High to Low, t _{PHL} CD4049UB | 5 | 5 | 32 | 65 | ns |
| | 10 | 10 | 20 | 40 | ns |
| | 10 | 5 | 15 | 30 | ns |
| | 15 | 15 | 15 | 30 | ns |
| | 15 | 5 | 10 | 20 | ns |
| Propagation Delay Time High to Low, t _{PHL} CD4050B | 5 | 5 | 55 | 110 | ns |
| | 10 | 10 | 22 | 55 | ns |
| | 10 | 5 | 50 | 100 | ns |
| | 15 | 15 | 15 | 30 | ns |
| | 15 | 5 | 50 | 100 | ns |
| Transition Time, Low to High, t _{TLH} | 5 | 5 | 80 | 160 | ns |
| | 10 | 10 | 40 | 80 | ns |
| | 15 | 15 | 30 | 60 | ns |
| Transition Time, High to Low, t _{THL} | 5 | 5 | 30 | 60 | ns |
| | 10 | 10 | 20 | 40 | ns |
| | 15 | 15 | 15 | 30 | ns |

CD4049UB, CD4050B

AC Electrical Specifications $T_A = 25^\circ\text{C}$, Input $t_r, t_f = 20\text{ns}$, $C_L = 50\text{pF}$, $R_L = 200\text{k}\Omega$ (Continued)

| PARAMETER | TEST CONDITIONS | | LIMITS (ALL PACKAGES) | | UNITS |
|---|-----------------|----------|-----------------------|------|-------|
| | V_{IN} | V_{CC} | TYP | MAX | |
| Input Capacitance, C_{IN} CD4049UB | - | - | 15 | 22.5 | pF |
| Input Capacitance, C_{IN} CD4050B | - | - | 5 | 7.5 | pF |

Typical Performance Curves

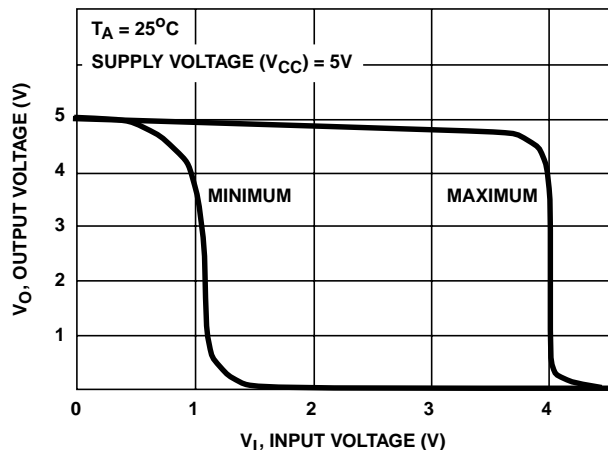


FIGURE 2. MINIMUM AND MAXIMUM VOLTAGE TRANSFER CHARACTERISTICS FOR CD4049UB

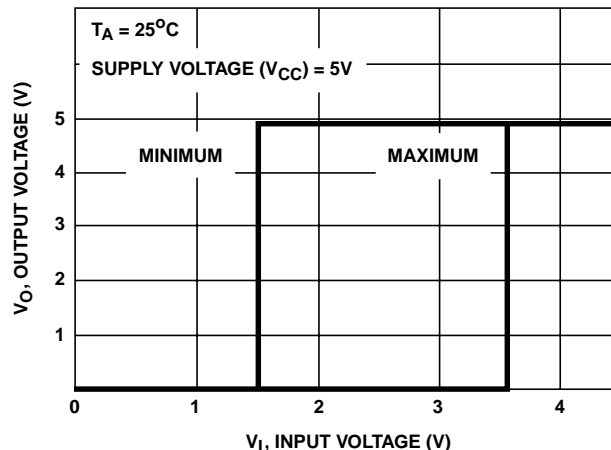


FIGURE 3. MINIMUM AND MAXIMUM VOLTAGE TRANSFER CHARACTERISTICS FOR CD4050B

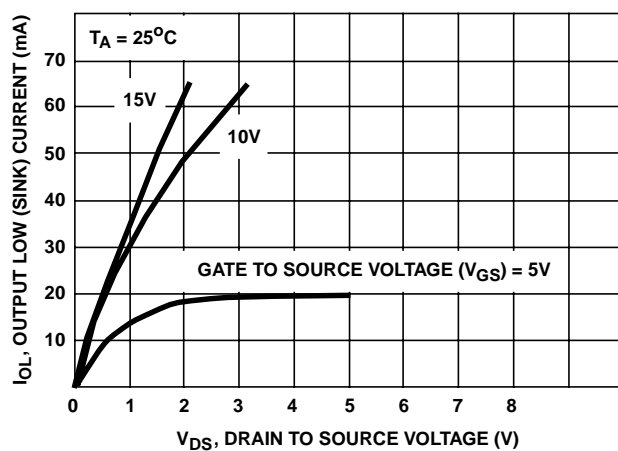


FIGURE 4. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

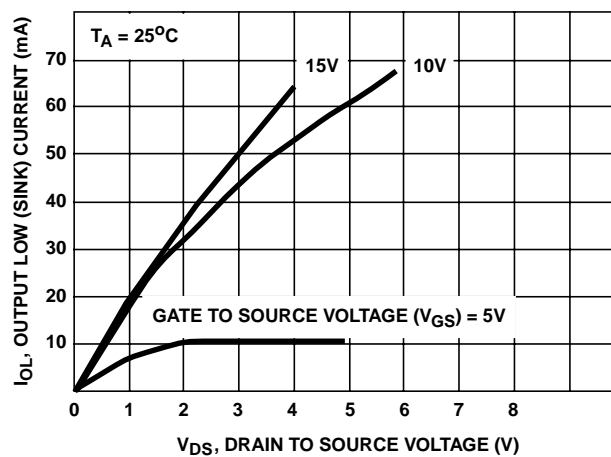


FIGURE 5. MINIMUM OUTPUT LOW (SINK) CURRENT DRAIN CHARACTERISTICS

Typical Performance Curves (Continued)

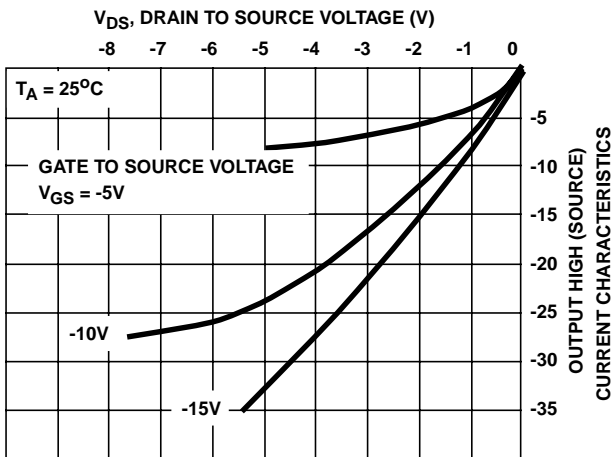


FIGURE 6. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

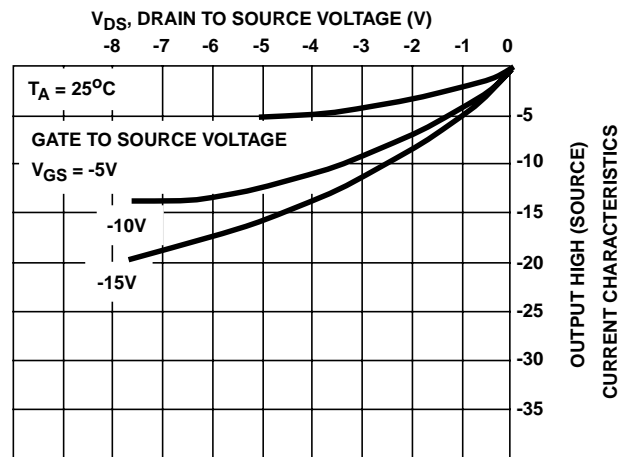


FIGURE 7. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

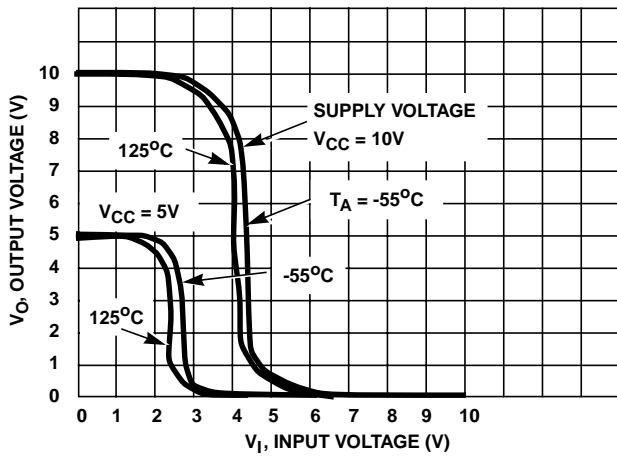


FIGURE 8. TYPICAL VOLTAGE TRANSFER CHARACTERISTICS AS A FUNCTION OF TEMPERATURE FOR CD4049UB

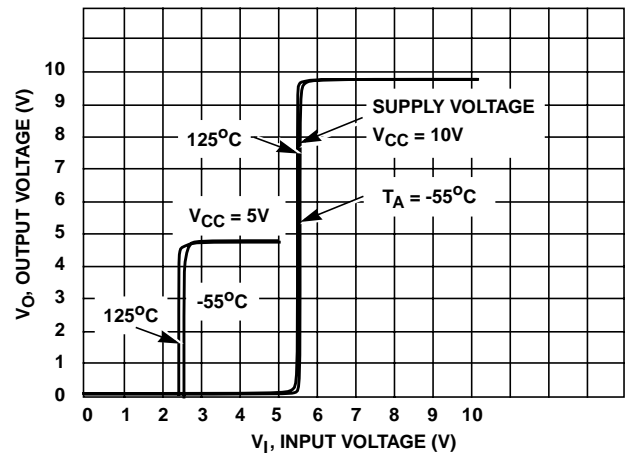


FIGURE 9. TYPICAL VOLTAGE TRANSFER CHARACTERISTICS AS A FUNCTION OF TEMPERATURE FOR CD4050B

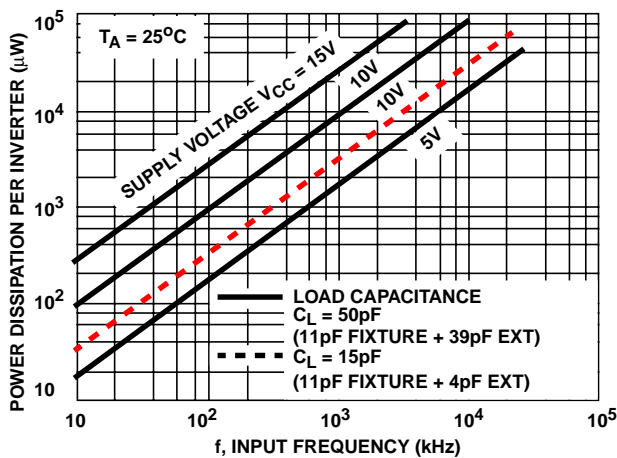


FIGURE 10. TYPICAL POWER DISSIPATION vs FREQUENCY CHARACTERISTICS

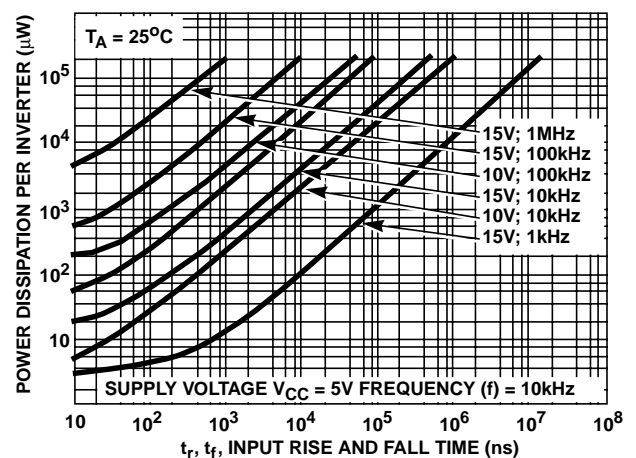


FIGURE 11. TYPICAL POWER DISSIPATION vs INPUT RISE AND FALL TIMES PER INVERTER FOR CD4049UB

Typical Performance Curves (Continued)

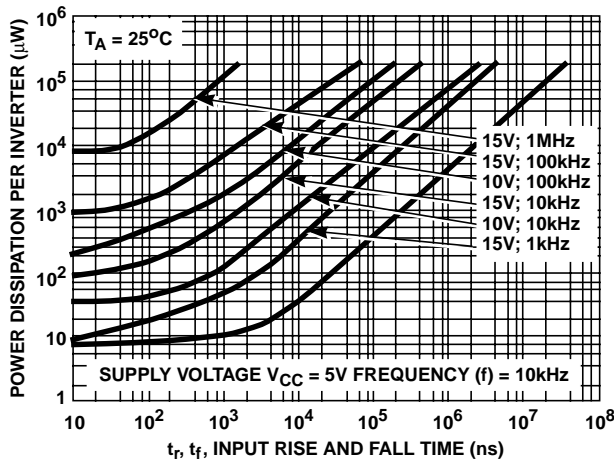


FIGURE 12. TYPICAL POWER DISSIPATION vs INPUT RISE AND FALL TIMES PER INVERTER FOR CD4050B

Test Circuits

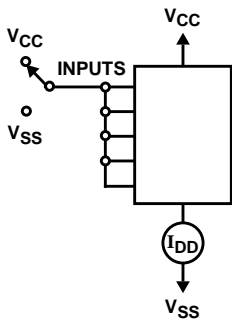
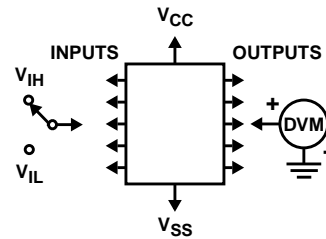
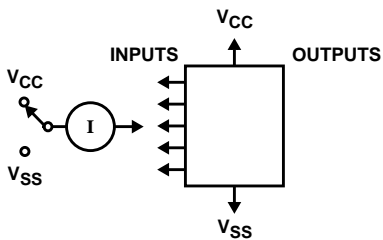


FIGURE 13. QUIESCENT DEVICE CURRENT TEST CIRCUIT



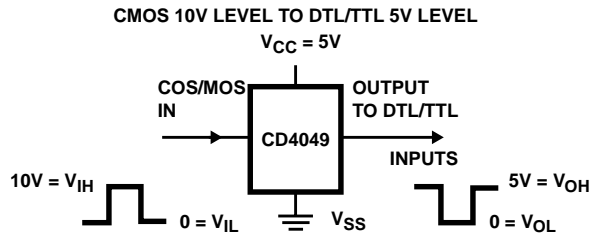
NOTE: Test any one input with other inputs at V_{CC} or V_{SS}.

FIGURE 14. INPUT VOLTAGE TEST CIRCUIT



NOTE: Measure inputs sequentially, to both V_{CC} and V_{SS} connect all unused inputs to either V_{CC} or V_{SS}.

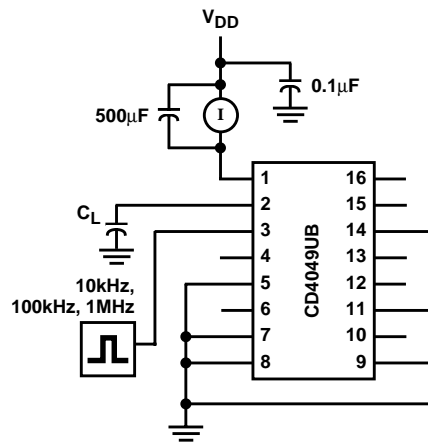
FIGURE 15. INPUT CURRENT TEST CIRCUIT



In Terminal - 3, 5, 7, 9, 11, or 14
 Out Terminal - 2, 4, 6, 10, 12 or 15
 V_{CC} Terminal - 1
 V_{SS} Terminal - 8

FIGURE 16. LOGIC LEVEL CONVERSION APPLICATION

Test Circuits (Continued)



C_L INCLUDES FIXTURE CAPACITANCE

FIGURE 17. DYNAMIC POWER DISSIPATION TEST CIRCUITS

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD4049UBD | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDWE4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDWG4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDWR | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDWRE4 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBDWRG4 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4049UBEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4049UBF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4049UBF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4049UBF3AS2283 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI |
| CD4049UBF3AS2534 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI |
| CD4049UBM | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI |
| CD4049UBM96 | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI |
| CD4049UBNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBNSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD4049UBPWE4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4049UBPWG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BD | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDWE4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDWG4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDWR | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDWRE4 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BDWRG4 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4050BEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4050BF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4050BF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4050BF3AS2283 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI |
| CD4050BF3AS2534 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI |
| CD4050BM | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI |
| CD4050BNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD4050BNSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BPWE4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4050BPWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| JM38510/05553BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/05554BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4049UBDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4049UBDWR | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |
| CD4049UBNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4049UBPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 7.0 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4050BDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4050BDWR | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |
| CD4050BNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4050BPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 7.0 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4049UBDR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD4049UBDWR | SOIC | DW | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4049UBNSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4049UBPWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |
| CD4050BDR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD4050BDWR | SOIC | DW | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4050BNSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4050BPWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN

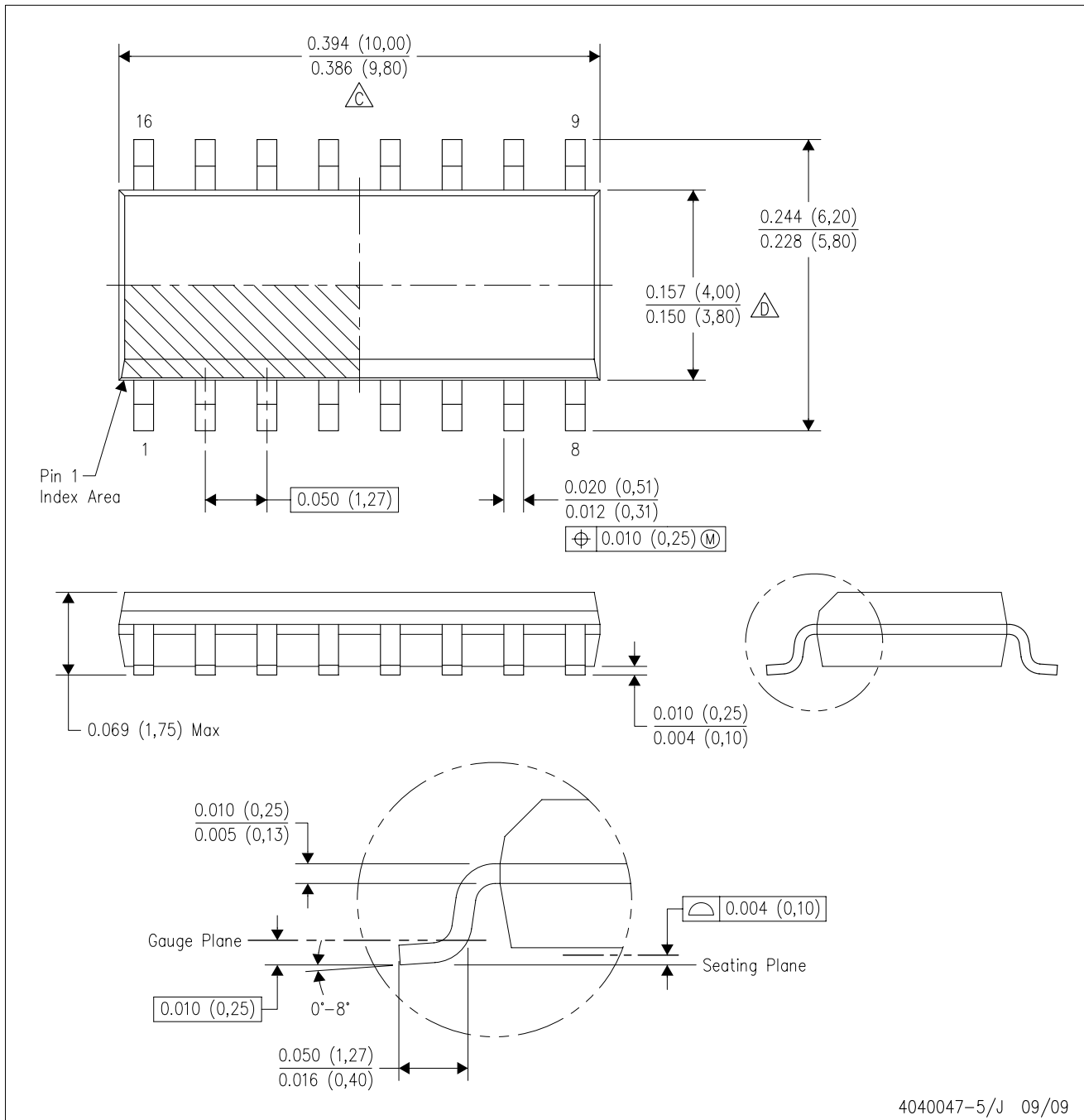


4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-5/J 09/09

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

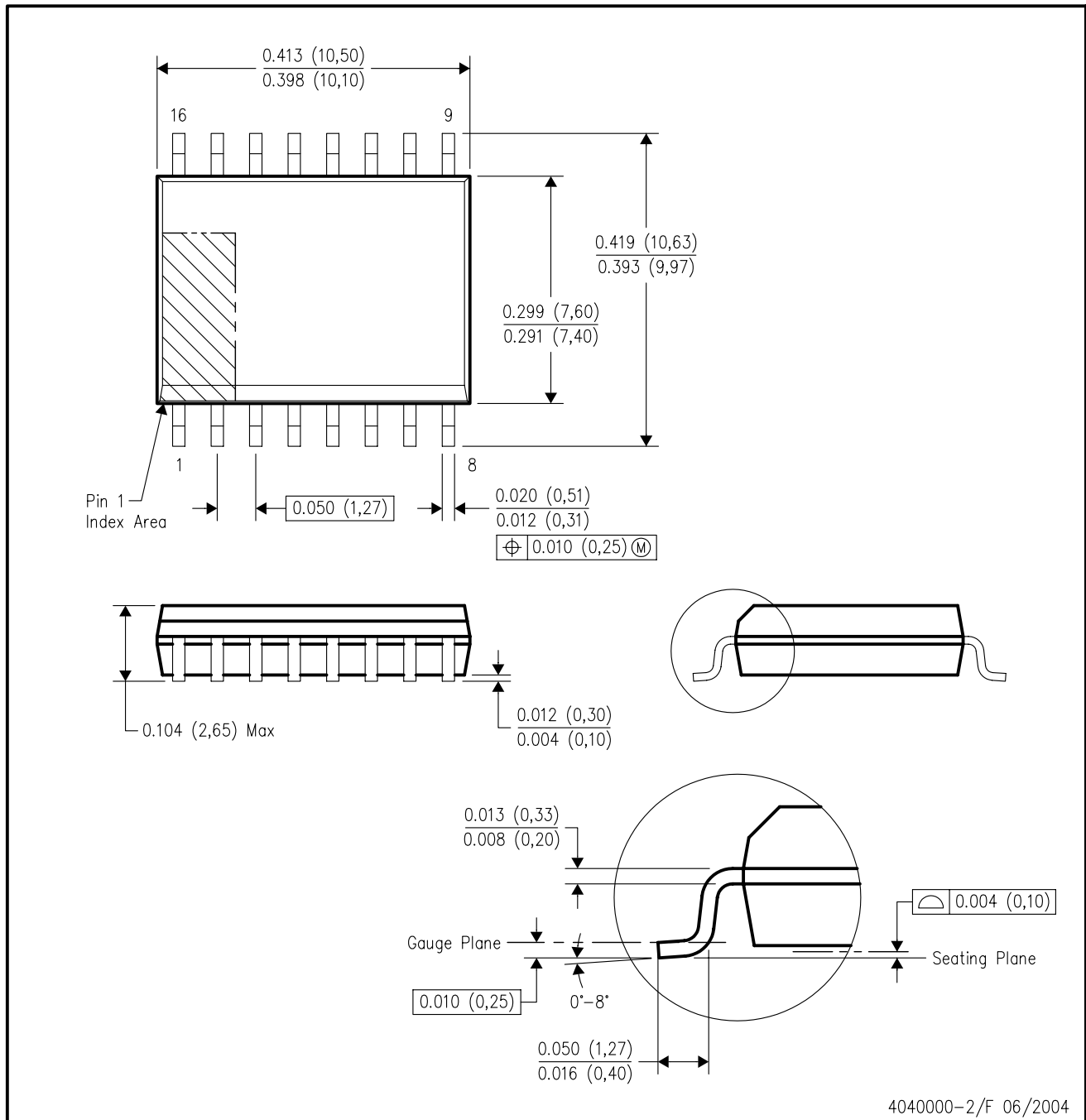
D(R-PDSO-G16)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



4040000-2/F 06/2004

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AA.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4049UBD | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDWE4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDWG4 | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDWR | ACTIVE | SOIC | DW | 16 | | TBD | Call TI | Call TI | -55 to 125 | CD4049UBM | Samples |
| CD4049UBDWRE4 | ACTIVE | SOIC | DW | 16 | | TBD | Call TI | Call TI | -55 to 125 | CD4049UBM | Samples |
| CD4049UBE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4049UBE | Samples |
| CD4049UBEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4049UBE | Samples |
| CD4049UBF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4049UBF | Samples |
| CD4049UBF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4049UBF3A | Samples |
| CD4049UBF3AS2283 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | | | |
| CD4049UBF3AS2534 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | | | |
| CD4049UBM | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4049UBM96 | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| CD4049UBNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UB | Samples |
| CD4049UBNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4049UB | Samples |
| CD4049UBPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM049UB | Samples |
| CD4049UBPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM049UB | Samples |
| CD4049UBPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM049UB | Samples |
| CD4049UBPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM049UB | Samples |
| CD4050BD | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BDE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BDR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BDRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BDT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BDW | ACTIVE | SOIC | DW | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BDWR | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BDWRE4 | ACTIVE | SOIC | DW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050BM | Samples |
| CD4050BE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4050BE | Samples |
| CD4050BEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4050BE | Samples |
| CD4050BF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4050BF | Samples |
| CD4050BF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4050BF3A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|---------|
| CD4050BF3AS2283 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | | | |
| CD4050BF3AS2534 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI | | | |
| CD4050BM | OBSOLETE | SOIC | D | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| CD4050BNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4050B | Samples |
| CD4050BPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM050B | Samples |
| CD4050BPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM050B | Samples |
| CD4050BPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM050B | Samples |
| JM38510/05553BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05553BEA | Samples |
| JM38510/05554BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05554BEA | Samples |
| M38510/05553BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05553BEA | Samples |
| M38510/05554BEA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05554BEA | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD4049UB, CD4049UB-MIL, CD4050B, CD4050B-MIL :

● Catalog: [CD4049UB](#), [CD4050B](#)

● Military: [CD4049UB-MIL](#), [CD4050B-MIL](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4049UBDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4049UBPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4050BDR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4050BDR | SOIC | DW | 16 | 2000 | 330.0 | 16.4 | 10.75 | 10.7 | 2.7 | 12.0 | 16.0 | Q1 |
| CD4050BPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4049UBDR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD4049UBPWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |
| CD4050BDR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD4050BDWR | SOIC | DW | 16 | 2000 | 367.0 | 367.0 | 38.0 |
| CD4050BPWR | TSSOP | PW | 16 | 2000 | 367.0 | 367.0 | 35.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211283-4/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040064-4/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

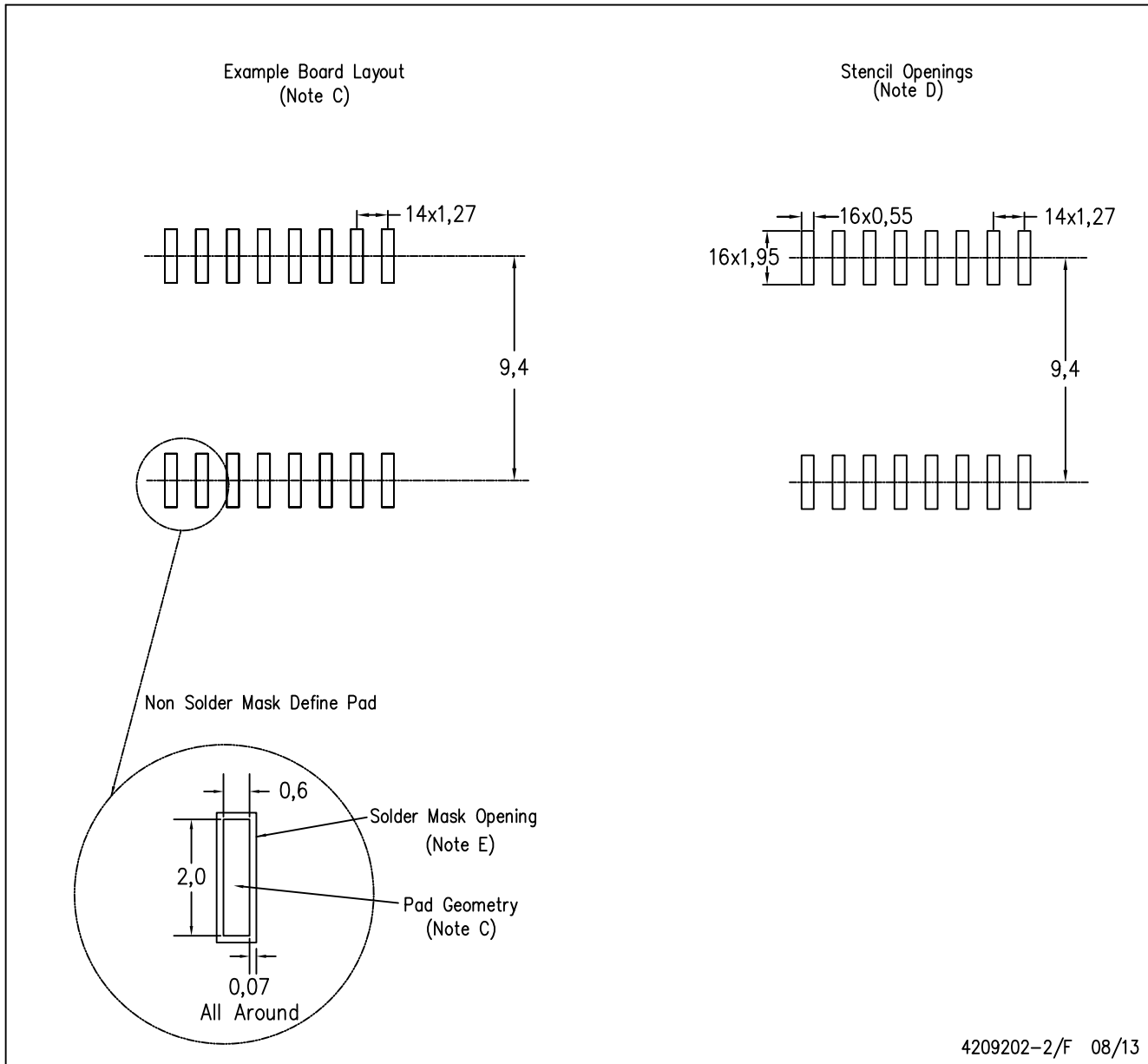
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AA.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4209202-2/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

| | |
|------------------------------|--|
| Audio | www.ti.com/audio |
| Amplifiers | amplifier.ti.com |
| Data Converters | dataconverter.ti.com |
| DLP® Products | www.dlp.com |
| DSP | dsp.ti.com |
| Clocks and Timers | www.ti.com/clocks |
| Interface | interface.ti.com |
| Logic | logic.ti.com |
| Power Mgmt | power.ti.com |
| Microcontrollers | microcontroller.ti.com |
| RFID | www.ti-rfid.com |
| OMAP Applications Processors | www.ti.com/omap |
| Wireless Connectivity | www.ti.com/wirelessconnectivity |

Applications

| | |
|-------------------------------|--|
| Automotive and Transportation | www.ti.com/automotive |
| Communications and Telecom | www.ti.com/communications |
| Computers and Peripherals | www.ti.com/computers |
| Consumer Electronics | www.ti.com/consumer-apps |
| Energy and Lighting | www.ti.com/energy |
| Industrial | www.ti.com/industrial |
| Medical | www.ti.com/medical |
| Security | www.ti.com/security |
| Space, Avionics and Defense | www.ti.com/space-avionics-defense |
| Video and Imaging | www.ti.com/video |

TI E2E Community

e2e.ti.com